

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

Claim 1 (Cancelled)

Claim 2 (Previously Presented) A circuit pattern inspection method of inspecting a pattern shape on the basis of two-dimensional distribution information of intensities of secondary electrons or reflected electrons obtained by observing a pattern formed on a substrate by a scanning microscope using a charged particle beam, comprising:

a step of detecting a set of edge points indicative of positions of line edges of said pattern in a two-dimensional plane from said two-dimensional distribution information by a threshold method;

a step of obtaining an approximation line for the set of edge points detected for each line edge by least square;

a step of obtaining an edge roughness shape by calculating the difference between the set of said edge points belonging to each line edge and said approximation line; and

a step of displaying correlation between edge roughness shapes of different line edges.

Claim 3 (Previously Presented) The circuit pattern inspection method according to claim 2, wherein a plurality of values are used as thresholds used for said threshold method.

Claim 4 (Original) The circuit pattern inspection method according to claim 3, further comprising a step of calculating a spatial frequency distribution of said edge roughness shape obtained.

Claim 5 (Previously Presented) The circuit pattern inspection method according to claim 3, further comprising a step of obtaining the degree of said edge roughness by calculating a standard deviation expressed by the square root of an average of root-mean-square values of the differences each between the set of said edge points derived with respect to said plurality of thresholds and said approximation line.

Claim 6 (Previously Presented) The circuit pattern inspection method according to claim 3, further comprising a step of selecting a candidate of a process of forming a pattern of said substrate, which causes occurrence of roughness from said edge roughness shape obtained, and displaying the candidate.

Claims 7-9 (Cancelled)

Claim 10 (Original) A circuit pattern inspection method of inspecting a pattern shape on the basis of two-dimensional distribution information of intensities of

secondary electrons or reflected electrons obtained by observing a pattern formed on a substrate by a scanning microscope using a charged particle beam, comprising:

- a step of detecting a set of edge points indicative of positions of edges of said pattern in a two-dimensional plane from said two-dimensional distribution information by a threshold method;

- a step of obtaining an approximation line for the set of edge points belonging to said edge detected;

- a step of obtaining an edge roughness shape by calculating the difference between the set of said edge points and said approximation line; and

- a step of selecting a candidate of a pattern forming process on said substrate as a cause of occurrence of roughness from said edge roughness shape obtained and displaying the candidate,

wherein a plurality of values are used as thresholds used for said threshold method.

Claim 11 (Cancelled)